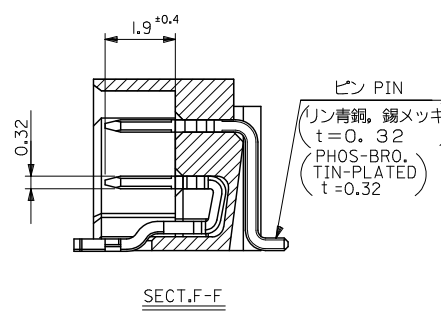
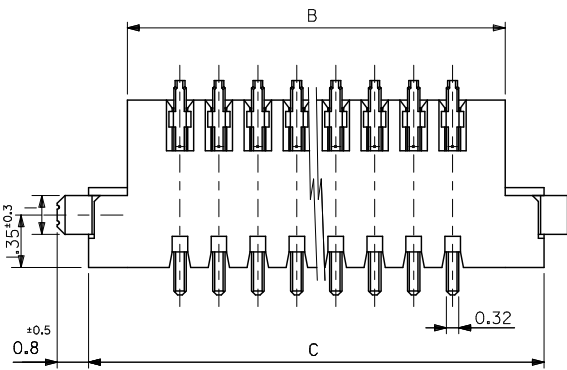
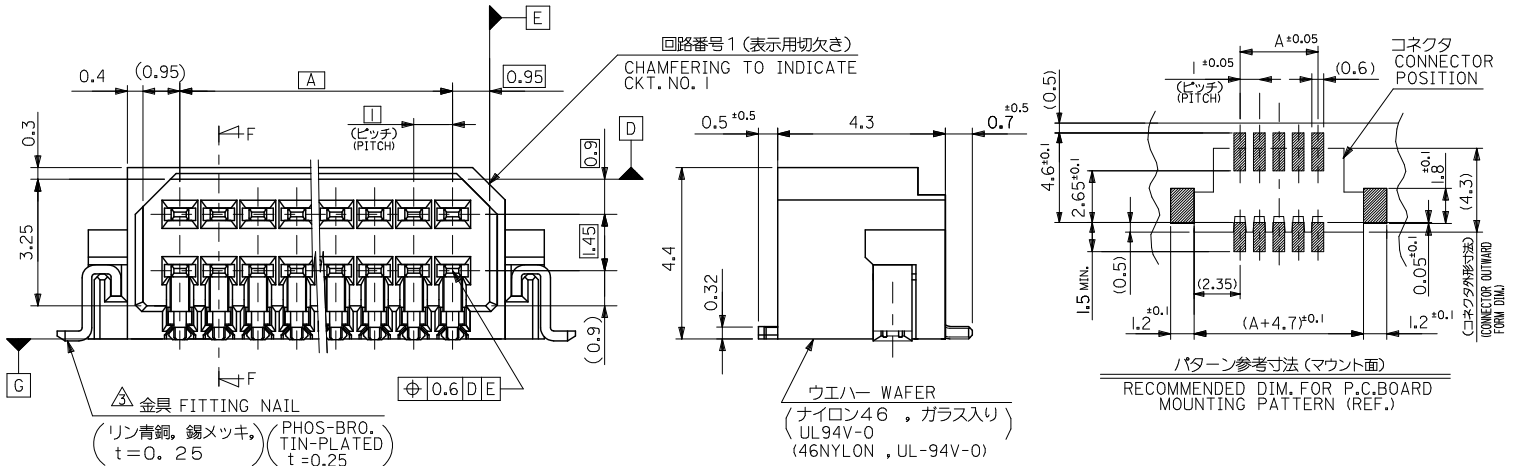


10 9 8 7 6 5 4 3 2 1



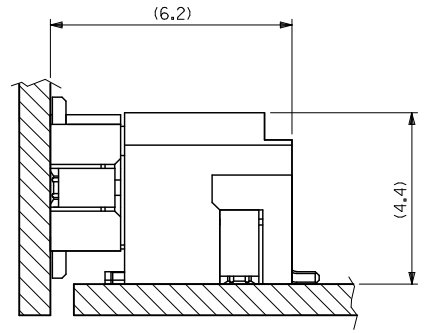
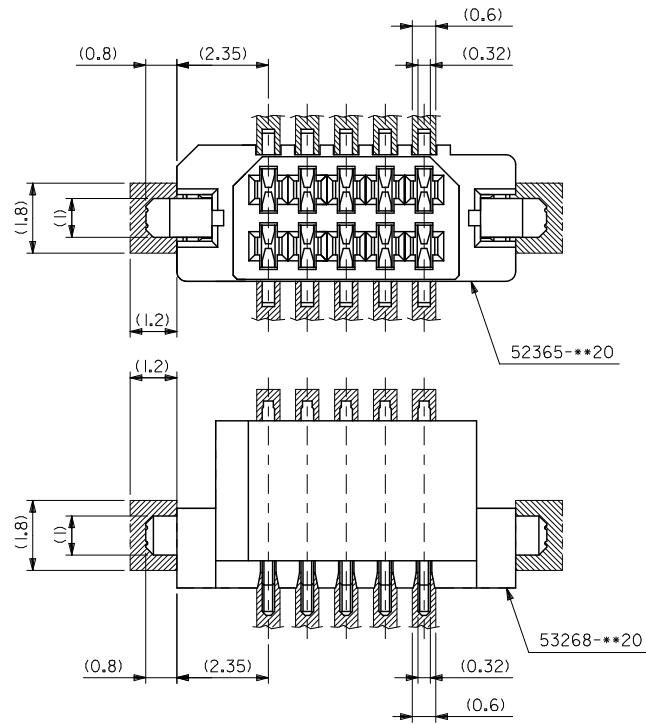
18.7	16.7	14	53268-3020	30
15.7	13.7	11	53268-2420	24
12.7	10.7	8	53268-1820	18
6.7	4.7	2	53268-0620	6
C	B	A	MATERIAL NO.	種数 (CIRCUIT)

**注記 NOTES.**

1. 嵌合相手 : 52365-\*\*\*10 , 52365-\*\*\*20  
MATES WITH : 52365-\*\*\*10 , 52365-\*\*\*20
2. ハウジングの底面 [G] からの金具及びターミナル半田付面のズレ量は上方0.1MAX. 下方0.15MAX. とする。  
MISALIGNMENT OF SOLDER TAIL TIP AND FITTING NAIL FROM [G]  
: UPPER DIRECTION 0.1mmMAX.  
: LOWER DIRECTION 0.15mmMAX.

△ パターンハクリ止め用金具  
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

REVISED EC NO: J2009-0666 DRAWN: KANAKURA 2008/09/25 CHKD: HARUYAMA 2008/09/25 APPR: NIKITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY S. AIHARA	DATE '92/8/3	TITLE 1.0 B/B CONN.WAFER ASS'Y R/A SMT (2/2)		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. FUKUSHIMA	DATE '92/8/4	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. ENOMOTO	DATE '92/8/4	DOCUMENT NO. SD-53268-011		
REV	DESCRIPTION	ANGULAR ±3°	MATERIAL NO. SEE TABLE	SIZE A3		SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



基板取付推奨レイアウト  
RECOMMENDED P.C.BOARD LAYOUT

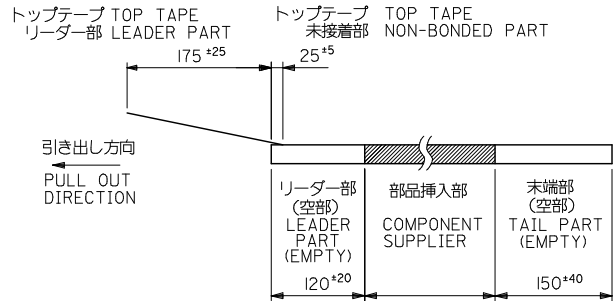
MODEL NO. 53268-\*\*\*20

REVISED IEC NO: J2009-0666 DRAWN: KANAKUBARA 2008/09/25 CHECKED: HARUYAMA 2008/09/25 APPROVED: ITO 2008/09/25 B	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	$\pm$ ---	DRAWN BY S. AIHARA	DATE '92/8/3	TITLE 1.0 B/B CONN.WAFER ASS'Y R/A SMT (2/2)			
	10 OVER 30 UNDER	$\pm$ ---	CHECKED BY M. FUKUSHIMA	DATE '92/8/4	MOLEX INCORPORATED			
	30 OVER	$\pm$ ---	APPROVED BY M. ENOMOTO	DATE '92/8/4	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-53268-011	SHEET NO. 2 OF 2	
ANGULAR		$\pm$ --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

CONFIDENTIAL

注記 NOTES

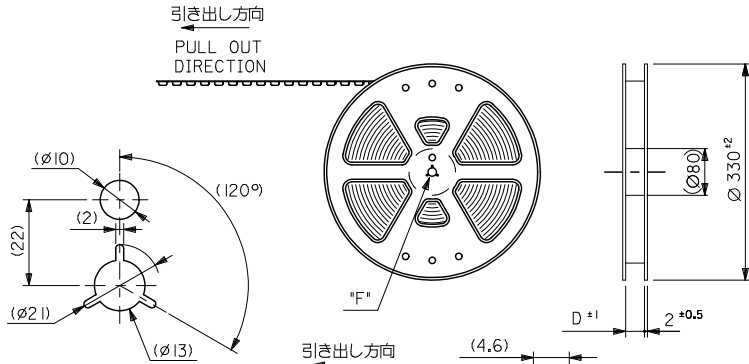
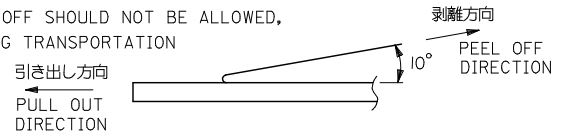
- 1. 梱包数量： 1000 個/リール NUMBER OF CONNECTORS: 1000PCS/REEL
- 2. リードテープ長さ LEAD TAPE LENGTH



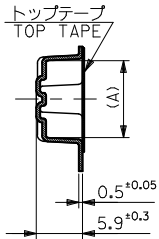
- 3. トップテープの剥離強度： (剥離方向は下図参照)

60gf MAX. 尚、本規格値は、出荷時に適用。  
(但し、輸送時に剥離が発生しない事。)

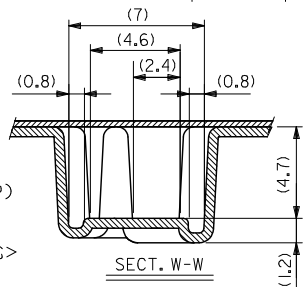
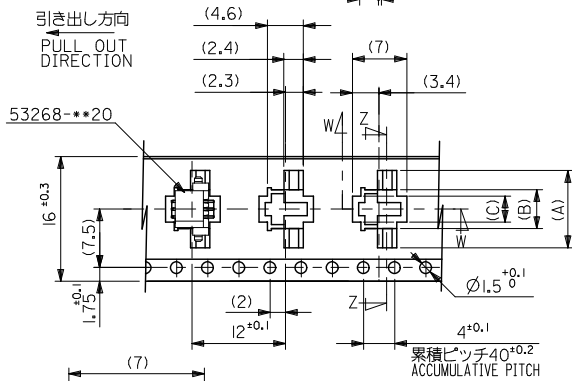
PEELING OFF FORCE OF TOP TAPE  
60gfMAX.(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
PEEL OFF SHOULD NOT BE ALLOWED,  
DURING TRANSPORTATION



DETAIL "F"



SECT. Z-Z



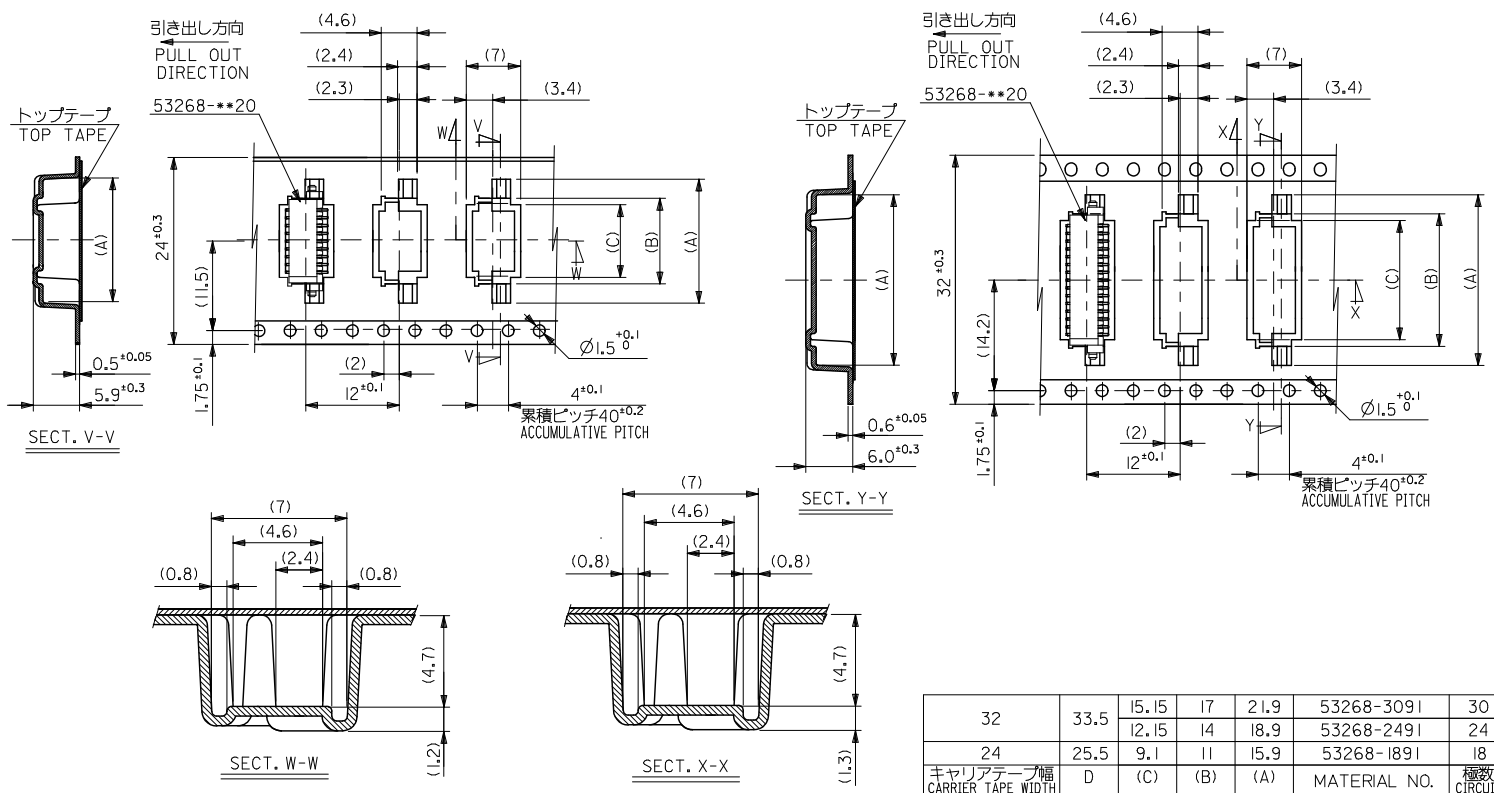
SECT. W-W

4. 材料  
 キャリアテープ: ポリプロピレン (PP)  
 トップテープ: PET, PE, PEF  
 リール: ポлистиレン (PS)  
 <リサイクル材を含む>
- MATERIAL  
 CARRIER TAPE: POLYPROPYLENE  
 TOP TAPE: PET, PE, PEF  
 REEL: POLYSTYRENE (PS)  
 <RECYCLE MATERIAL  
 CONTAINED>

16	17.5	3.1	5	9.9	53268-0691	6
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	極致 CIRCUIT
					MODEL NO.	53268-***91

REVISED EC NO: J2009-0666 DRAWN: KURARA 2008/09/25 CHKD: HARUYAMA 2008/09/25 APPR: NIKITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY T. HARUYAMA	DATE '90/5/8	TITLE 1.0 BTB CONN WAFER ASSY RA SMT EMBSTP PKG (1/2)	
	10 OVER 30 UNDER	± ---	CHECKED BY T. ITO	DATE '00/12/6	MOLEX INCORPORATED	
	30 OVER	± ---	APPROVED BY M. FUKUSHIMA	DATE '00/12/6	DOCUMENT NO. SD-53268-012	SHEET NO. 1 OF 2
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



32	33.5	15.15	17	21.9	53268-3091	30
24	25.5	12.15	14	18.9	53268-2491	24
キャリアテープ幅 CARRIER TAPE WIDTH	D	9.1	11	15.9	53268-1891	18
					MATERIAL NO.	極致 CIRCUIT

MODEL NO. 53268-\*\*91

REVISED ELC NO: J2009-0666 川崎 2008/09/25 川崎 2008/09/25 川崎 2008/09/25 川崎 2008/09/25 川崎 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±---	DRAWN BY T. HARUYAMA	DATE '90/5/8	TITLE 1.0 BTB CONN WAFER ASSY RA SMT EMBSTP PKG (2/2)		
	10 OVER 30 UNDER	±---	CHECKED BY T. ITO	DATE '00/12/6	MOLEX INCORPORATED		
	30 OVER	±---	APPROVED BY M. FUKUSHIMA	DATE '00/12/6	DOCUMENT NO. SD-53268-012		
	ANGULAR	±--- °	MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					